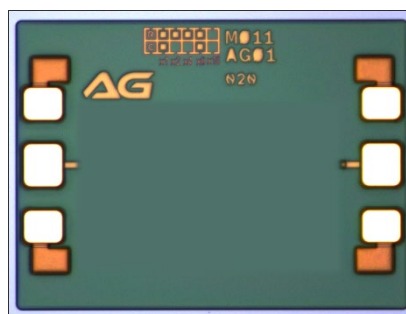
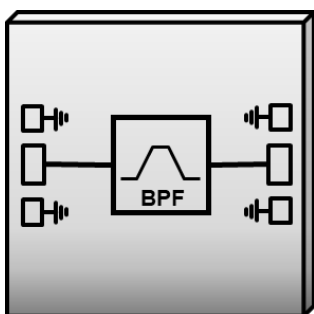


Typical Applications

- Communication Systems
- Point to Point Radio
- Fiber Optics
- Test Equipment
- Wideband Military & Space

Features

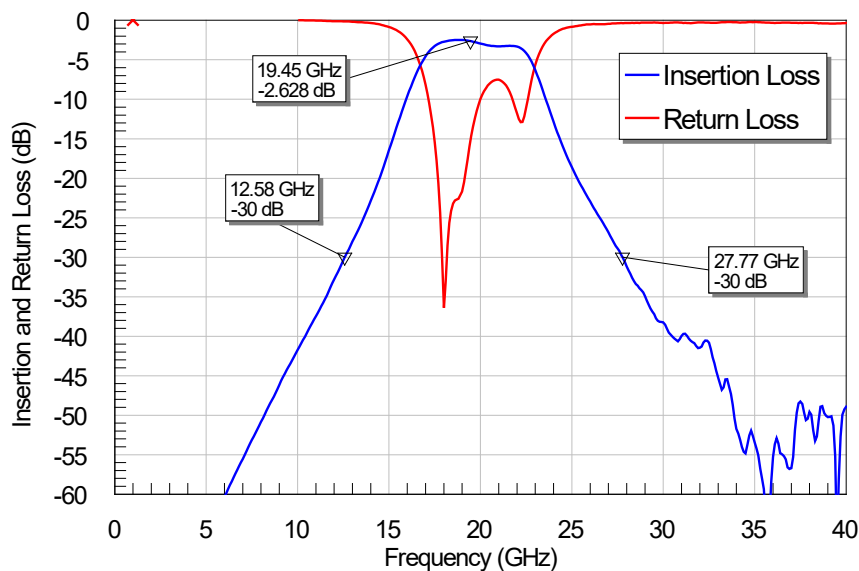
- Center Frequency: 19.45GHz
- Passband Loss: 2.6dB @ 19.45GHz
- Rejection: 30dB at 12.58GHz and 27.77GHz
- 50Ω Matched DC blocked RF Ports
- Chip Size: 1.00 x 0.750 x 0.1 mm²



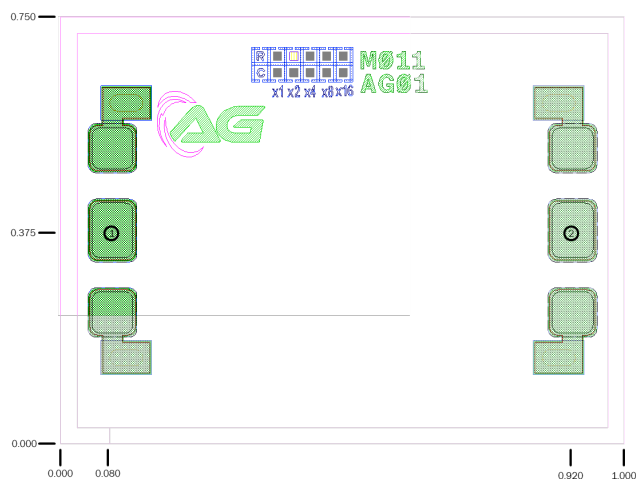
Parameter	Units	Minimum	Typical	Maximum
Frequency	GHz	17.52		21.45
Passband Loss	dB		2.6	3.88
Passband Return Loss	dB			8
Rejection 30dB Point	GHz	12.58		27.77
Package Type			Die	

Performance Graphs

Gain and Return Loss



Outline Drawing (dimensions in mm)



Pad Descriptions

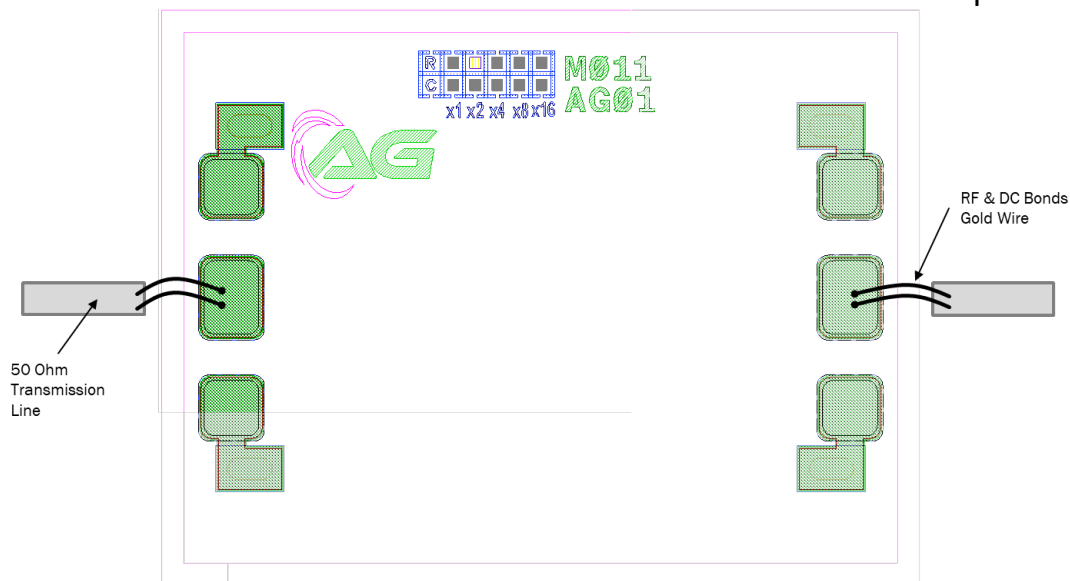
Pad	Function	Pad Size	Description
1	RFIN	75x100μm	DC blocked 50Ω Matched
2	RFOUT	75x100μm	DC blocked 50Ω Matched
Die Bottom	GND	Backside	Epoxy/Solder to Baseplate

Absolute Maximum Ratings

Drain Bias Voltage (VDD)	No Bias
RF Input Power (RFIN)	+20dBm*
Channel Temperature	150°C
Storage Temperature	-65 to 150°C
Operating Temperature	-55 to 85°C

Assembly Diagrams

GaAs pHEMT MMIC 19.45GHz Bandpass Filter



Assembly Notes:

1. Die Thickness is 100 μ m
2. Backside and Bondpad metallization: 4 μ m gold
3. Silver Epoxy or AuSn Eutectic attach MMIC



Die Packaging Information

- GP-8 (Gel-Pak)